

# Control iD

## PCB Stack-up and Technical Requirements

Our minimum specifications are as follow:

Number of layers:	<b>2 layers</b>
Minimum line width (<=):	<b>8 mils</b>
Minimum line spacing/gap (<=):	<b>8 mils</b>
Minimum Annular Ring (<=):	<b>8 mils</b>
Minimum mechanical hole size (<=):	<b>0,3mm</b>
Surface finish:	<b>HASL</b>
Electrical Test:	<b>100% Electrical Test (E-Test)</b>
Substrate type:	<b>FR-4</b>

### Stencil:

The global fiducials for the stencil are indicated on the **top-left, bottom-left and bottom-right** corners of the stencil files. The fiducials shall not be considered as openings for solder paste. The stencil shall be made in **stainless steel** and **laser cut**. The fiducials shall be produced in order to ensure good alignment and many production cycles. **Stencil thickness is 5mils.**

Please quote 1 stencil, **FRAMED using the standard 29" frame.**

### PCB Stack-up and files:

Layer name	Thickness (mm)	File extension
Silkscreen Top (White)	-	*.GTL
Soldermask Top (Red)	-	*.GTS
Copper Top	0,036	*.GTL
Dielectric	1,5	-
Copper Bottom	0,036	*.GBL
Soldermask Bottom (Red)	-	*.GBS
Silkscreen Bottom (White)	-	*.GBO

Total thickness	1,572
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File type	File Extension
Stencil top	*.GTP
Board outline	*.GM1
Drill information (2.5 / Leading zero suppression) (All vias are 100% pass through)	*.TXT